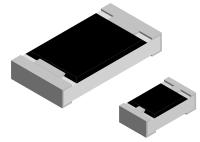


Vishay

COMPLIANT HALOGEN

FREE

### Lead (Pb)-Free Thick Film, Rectangular High Value Chip Resistor



### FEATURES

- High resistance values (up to 470M)
- · Suitable for voltage dividers and hybrids
- Pure tin plating provides compatibility with lead (Pb)-free and lead containing soldering processing
- Metal glaze on high quality ceramic
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

STANDARD ELECTRICAL SPECIFICATIONS									
MODEL	CASE SIZE INCH	CASE SIZE METRIC	POWER RATING P <sub>70</sub> W	LIMITING ELEMENT VOLTAGE U <sub>max.</sub> AC <sub>RMS</sub> /DC V	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	RESISTANCE RANGE Ω	SERIES	
D11/CRCW0603-HR	0603	RR 1608M	0.10	75	± 500	± 5	11M to 470M	E24	
D12/CRCW0805-HR	0805	RR 2012M	0.125	150	± 500	± 5	11M to 470M	E24	
D25/CRCW1206-HR	1206	RR 3216M	0.25	200	± 500	± 5	11M to 470M	E24	

Notes

• These resistors do not feature a limited lifetime when operated within the limits of rated dissipation, permissible operating voltage, and permissible film temperature. However, the resistance typically increase due to the resistor's film temperature over operating time, generally known as drift. The drift may exceed the stability requirements of an individual application circuit and thereby limits the functional time.

Marking and packaging: See datasheet "Surface Mount Resistor Marking" (<u>www.vishay.com/doc?20020</u>)

• Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material.

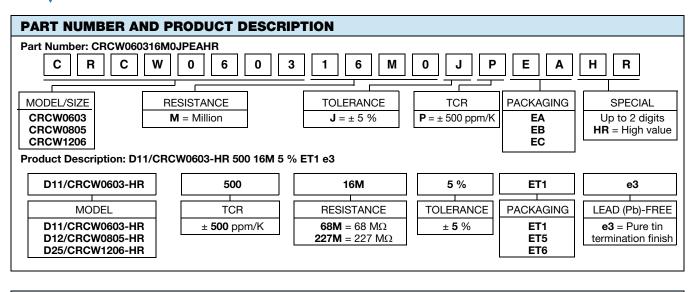
TECHNICAL SPECIFICATIONS						
PARAMETER	UNIT	D11/CRCW0603-HR	D12/CRCW0805-HR	D25/CRCW1206-HR		
Rated Dissipation at $P_{70}$ <sup>(1)</sup>	W	0.1	0.125	0.25		
Operating Voltage Umax. ACRMS/DC	V	75	150	200		
Voltage Coefficient	%/V		< 100M: < 0.1 > 100M: < 0.3			
Insulation Voltage U <sub>ins</sub> (1 min)	V	100 200 300				
Insulation Resistance	Ω	> 10 <sup>9</sup>				
Operating Temperature Range °C - 55 to + 155						
Weight	mg	2	5.5	10		

#### Note

<sup>(1)</sup> The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of 155 °C is not exceeded.

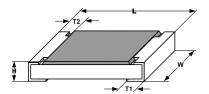
www.vishay.com

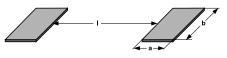
SHA



PACKAGING							
MODEL	CODE	QUANTITY	CARRIER TAPE	WIDTH	PITCH	REEL DIAMETER	
	EA = ET1	5000		8 mm	4 mm	180 mm/7"	
D11/CRCW0603-HR	EB = ET5	10 000				285 mm/11.25"	
	EC = ET6	20 000				330 mm/13"	
	EA = ET1	5000	Paper tape acc. to	8 mm	4 mm	180 mm/7"	
D12/CRCW0805-HR	EB = ET5	10 000	IEC 60068-3			285 mm/11.25"	
	EC = ET6	20 000	Type I			330 mm/13"	
	EA = ET1	5000			4 mm	180 mm/7"	
D25/CRCW1206-HR	EB = ET5	10 000		8 mm		285 mm/11.25"	
	EC = ET6	20 000				330 mm/13"	

#### DIMENSIONS





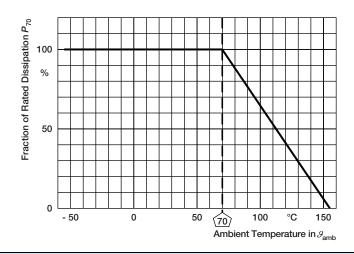
	SIZE DIMENSIONS in millimeters						SOLDER PAD DIMENSIONS in millimeters					
3	SIZE DIMENSIONS in minimeters					REFLOW SOLDERING			WAVE SOLDERING			
INCH	METRIC	L	w	н	T1	T2	а	b	I	а	b	I
0603	1608	1.55 <sup>+ 0.10</sup> - 0.05	0.85 ± 0.1	$0.45 \pm 0.05$	0.3 ± 0.2	0.3 ± 0.2	0.5	0.9	1.0	0.9	0.9	1.0
0805	2012	2.0 + 0.20 - 0.10	1.25 ± 0.15	$0.45 \pm 0.05$	0.3 + 0.10 - 0.20	0.3 ± 0.2	0.7	1.3	1.2	0.9	1.3	1.3
1206	3216	3.2 <sup>+ 0.10</sup> - 0.20	1.6 ± 0.15	$0.55 \pm 0.05$	0.45 ± 0.2	$0.4 \pm 0.2$	0.9	1.7	2.0	1.1	1.7	2.3

www.vishay.com

Vishay

#### DERATING

SHAY



TEST PRO	TEST PROCEDURES AND REQUIREMENTS						
EN 60115-1	IEC 60068-2 TEST	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR) STABILITY CLASS 2 OR BETTER			
CLAUSE	METHOD						
			Stability for product types:				
			D/CRCW-HR e3	11 MΩ to 470 MΩ			
4.5	_	Resistance	-	± 5 %			
4.13	-	Short time overload	$U = 2.5 \text{ x } \sqrt{P_{70} \text{ x } R} \le 2 \text{ x } U_{\text{max.}};$ Duration acc. to style	± (0.5 % <i>R</i> + 0.05 Ω)			
			Solder bath method; Sn60Pb40	Good tinning (≥ 95 % covered); no visible damage			
4.17.2	58 (Td)	Solderability	Solder bath method; Sn96, 5Ag3Cu0.5 or Sn99, 3Cu0.7 non-activated flux; (245 ± 5) °C or (250 ± 5) °C (3 ± 0.3) s	Good tinning (≥ 95 % covered); no visible damage			
4.8.4.2	_	Temperature coefficient	20 °C/- 55 °C/20 °C and 20 °C/125 °/20 °C	± 500 ppm/K			
4.32	21 (Uu <sub>3</sub> )	Shear (adhesion)	RR 1608: 9 N RR 2012 and RR 3216: 45N	No visible damage			
4.33	21 (Uu <sub>1</sub> )	Substrate bending	Depth 2 mm; 3 times	No visible damage, no open circuit in bent position $\pm (0.25 \% R + 0.05 \Omega)$			
4.19	14 (Na)	Rapid change of temperature	30 min. at - 55 °C; 30 min. at 125 °C 5 cycles 1000 cycles	± (0.5 % <i>R</i> + 0.05 Ω) ± (1 % <i>R</i> + 0.05 Ω)			
4.23 4.23.2 4.23.3	2 (Ba) 30 (Db)	Climatic sequence: Dry Heat Damp heat, cyclic	125 °C; 16 h 55 °C; ≥ 90 % RH;				
4.23.4 4.23.5 4.23.6	1 (Aa) 13 (M) 30 (Db)	Cold Low air pressure Damp heat, cyclic	24 h; 1 cycle - 55 °C; 2 h 1 kPa; (25 ± 10) °C; 1 h 55 °C; ≥ 90 % RH 24 h; 5 cycle	± (2 % <i>R</i> + 0.1 Ω)			
4.23.7	-	D.C. Load	$U = \sqrt{P_{70}} \times R$				

3

For technical questions, contact: <u>thickfilmchip@vishay.com</u> THIS DOCUMENT IS SUBJECT TO CHANGE WITHOUT NOTICE. THE PRODUCTS DESCRIBED HEREIN AND THIS DOCUMENT ARE SUBJECT TO SPECIFIC DISCLAIMERS, SET FORTH AT <u>www.vishay.com/doc?91000</u>



www.vishay.com

Vishay

TEST PROCEDURES AND REQUIREMENTS						
EN 60115-1 CLAUSE	IEC 60068-2 TEST	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (∆R)		
CLAUSE	METHOD			STABILITY CLASS 2 OR BETTER		
			Stability for product types:			
			D/CRCW-HR e3	11 M $\Omega$ to 470 M $\Omega$		
4.25.1	_	Endurance at 70 °C	U = √P <sub>70</sub> x R ≤ U <sub>max.</sub> 1.5 h on; 0,5 h off; 70 °C; 1000 h 70 °C; 8000 h	± (2 % <i>R</i> + 0.1 Ω) ± (4 % <i>R</i> + 0.1 Ω)		
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method (260 ± 5) °C; (10 ± 1) s	± (0.5 % <i>R</i> + 0.05 Ω)		
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; (93 ± 3) % RH; 56 days	$\pm$ (2 % R + 0.1 Ω)		
4.25.3	_	Endurance at upper category temperature	155 °C; 1000 h	$\pm$ (2 % R + 0.1 Ω)		

All tests are carried out in accordance with the following specifications:

- EN 60115-1, generic specification
- EN 140400, sectional specification
- EN 140401-802, detail specification
- IEC 60068-2-x, variety of environmental test procedures

Packaging of components is done in paper or blister tapes according to IEC 60286-3.

Revision: 12-Jun-12

4
For technical questions, contact: <u>thickfilmchip@vishay.com</u>



Vishay

## Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

# **Material Category Policy**

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.